

# NST489AMT1G, NSVT489AMT1G

## High Current Surface Mount NPN Silicon Low $V_{CE(sat)}$ Switching Transistor for Load Management in Portable Applications

### Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ )

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	$V_{CEO}$	30	V
Collector-Base Voltage	$V_{CBO}$	50	V
Emitter-Base Voltage	$V_{EBO}$	5.0	V
Collector Current – Continuous	$I_C$	2.0	A
Collector Current – Peak	$I_{CM}$	3.0	A

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$ (Note 1)	535 4.3	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 1)	234	$^\circ\text{C}/\text{W}$
Total Device Dissipation $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$ (Note 2)	1.180 9.4	W mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$ (Note 2)	106	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Lead #1	$R_{\theta JL}$ (Note 1) $R_{\theta JL}$ (Note 2)	110 50	$^\circ\text{C}/\text{W}$ $^\circ\text{C}/\text{W}$
Total Device Dissipation (Single Pulse < 10 s)	$P_{D\text{single}}$ (Notes 2 and 3)	1.75	W
Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 with 1 oz and  $3.9\text{ mm}^2$  of copper area.
2. FR-4 with 1 oz and  $645\text{ mm}^2$  of copper area.
3. Refer to Figure 8.



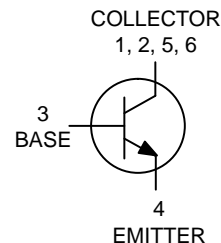
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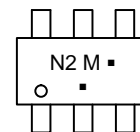
30 VOLTS, 3.0 AMPS  
NPN TRANSISTOR



TSOP-6  
CASE 318G  
STYLE 6



### DEVICE MARKING



N2 = Specific Device Code  
M = Date Code\*  
▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation may vary depending upon manufacturing location.

### ORDERING INFORMATION

Device	Package	Shipping†
NST489AMT1G	TSOP-6 (Pb-Free)	3,000 / Tape & Reel
NSVT489AMT1G	TSOP-6 (Pb-Free)	3,000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit	
<b>OFF CHARACTERISTICS</b>						
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 10 mA, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	30	–	–	V	
Collector–Base Breakdown Voltage (I <sub>C</sub> = 0.1 mA, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	50	–	–	V	
Emitter–Base Breakdown Voltage (I <sub>E</sub> = 0.1 mA, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	5.0	–	–	V	
Collector Cutoff Current (V <sub>CB</sub> = 30 V, I <sub>E</sub> = 0)	I <sub>CBO</sub>	–	–	0.1	μA	
Collector–Emitter Cutoff Current (V <sub>CE</sub> = 30 V)	I <sub>CES</sub>	–	–	0.1	μA	
Emitter Cutoff Current (V <sub>EB</sub> = 4.0 V)	I <sub>EBO</sub>	–	–	0.1	μA	
<b>ON CHARACTERISTICS</b>						
DC Current Gain (Note 4)	(I <sub>C</sub> = 1.0 mA, V <sub>CE</sub> = 5.0 V) (I <sub>C</sub> = 0.5 A, V <sub>CE</sub> = 5.0 V) (I <sub>C</sub> = 1.0 A, V <sub>CE</sub> = 5.0 V)	h <sub>FE</sub>	300 300 200	– 500 –	– 900 –	
Collector–Emitter Saturation Voltage (Note 4)	(I <sub>C</sub> = 1.0 A, I <sub>B</sub> = 100 mA) (I <sub>C</sub> = 0.5 A, I <sub>B</sub> = 50 mA) (I <sub>C</sub> = 0.1 A, I <sub>B</sub> = 1.0 mA)	V <sub>CE(sat)</sub>	– – –	0.10 0.06 0.05	0.200 0.125 0.075	V
Base–Emitter Saturation Voltage (Note 4) (I <sub>C</sub> = 1.0 A, I <sub>B</sub> = 0.1 A)		V <sub>BE(sat)</sub>	–	–	1.1	V
Base–Emitter Turn-on Voltage (Note 4) (I <sub>C</sub> = 1.0 A, V <sub>CE</sub> = 2.0 V)		V <sub>BE(on)</sub>	–	–	1.1	V
Cutoff Frequency (I <sub>C</sub> = 100 mA, V <sub>CE</sub> = 5.0 V, f = 100 MHz)		f <sub>T</sub>	200	300	–	MHz
Output Capacitance (f = 1.0 MHz)		C <sub>obo</sub>	–	–	15	pF

4. Pulsed Condition: Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

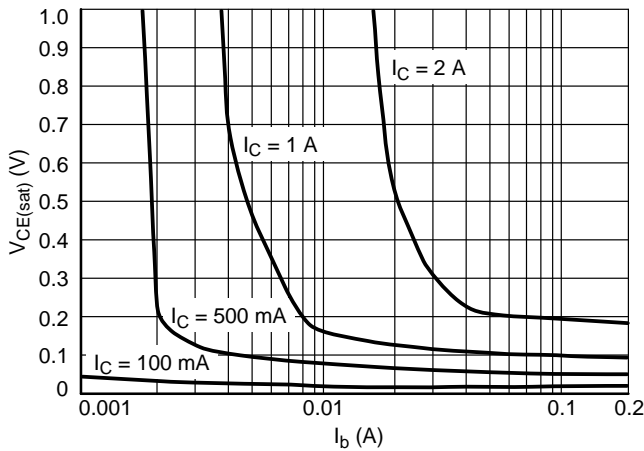


Figure 1. V<sub>CE(sat)</sub> versus I<sub>b</sub>

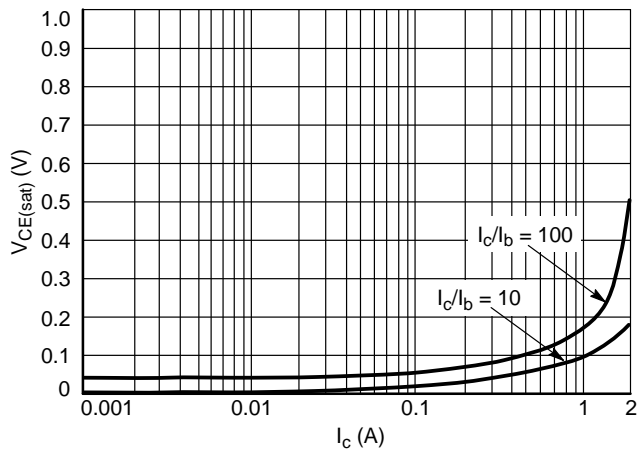


Figure 2. V<sub>CE(sat)</sub> versus I<sub>c</sub>

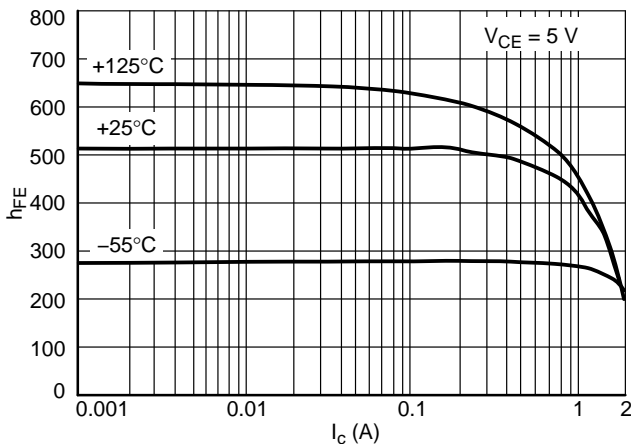


Figure 3. h<sub>FE</sub> versus I<sub>c</sub>

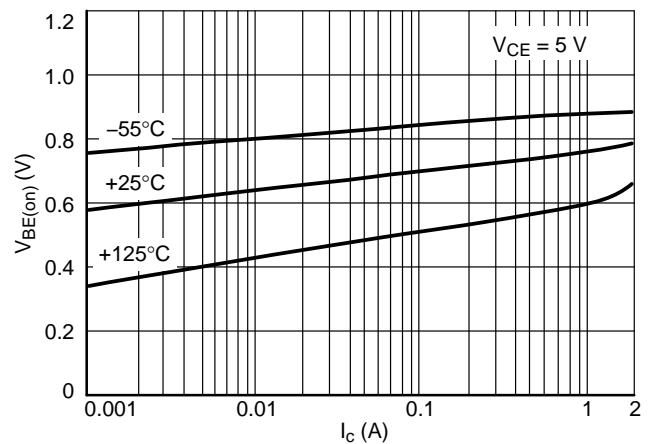


Figure 4. V<sub>BE(on)</sub> versus I<sub>c</sub>

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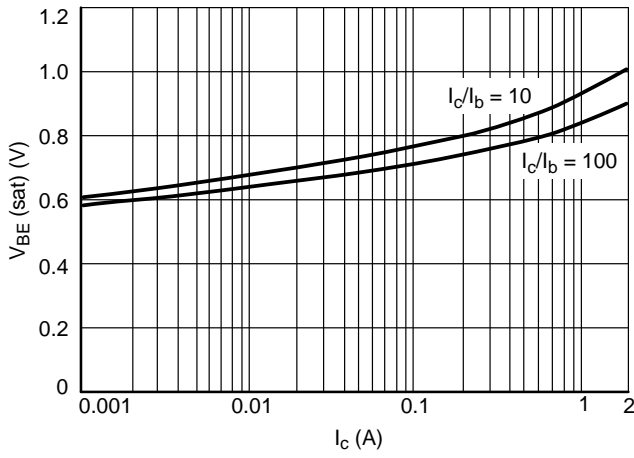


Figure 5.  $V_{BE(sat)}$  versus  $I_C$

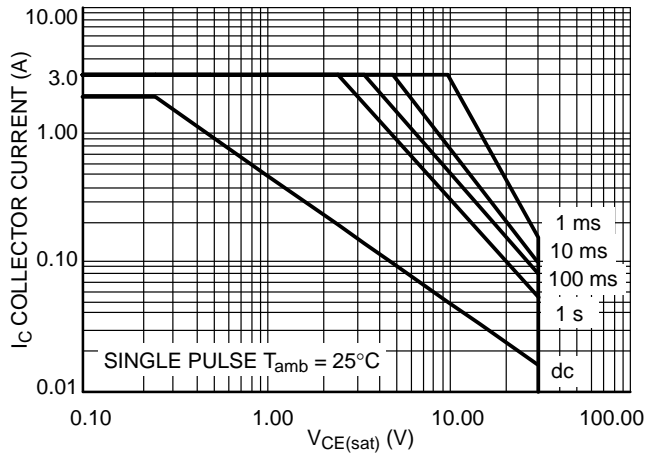


Figure 6. Safe Operating Area

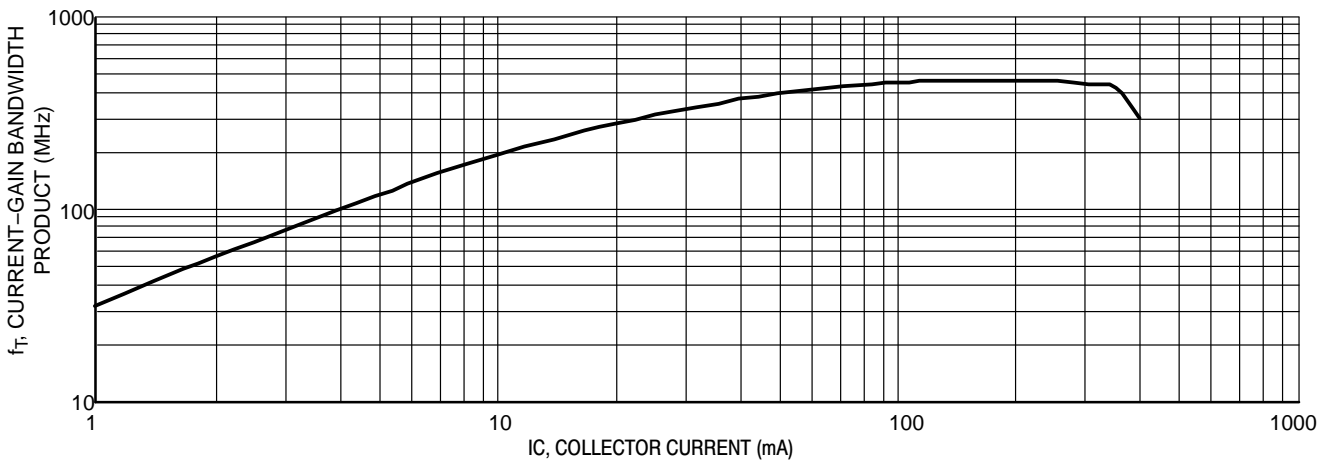


Figure 7.  $f_T$  (MHz) versus  $I_C$  (mA)  $V_{CE} = 5.0$  V

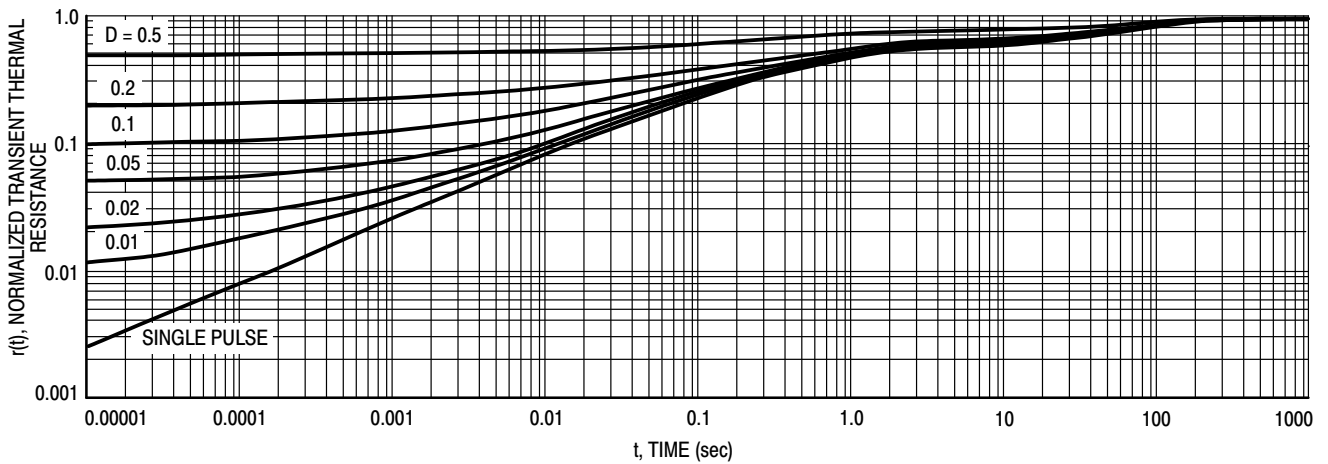
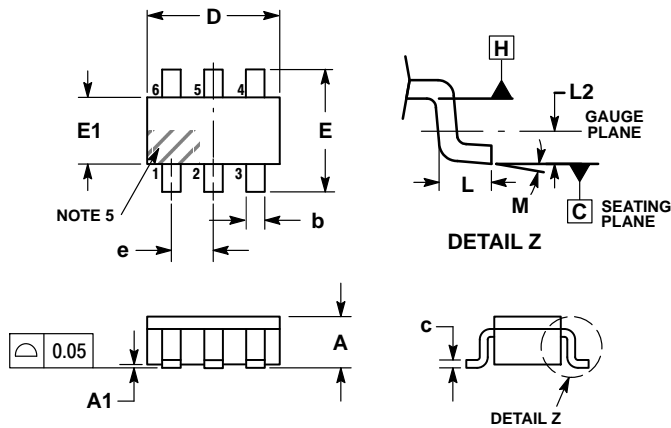


Figure 8. Normalized Thermal Response

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## PACKAGE DIMENSIONS

### TSOP-6 CASE 318G-02 ISSUE V



#### NOTES:

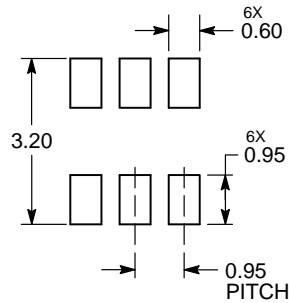
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE. DIMENSIONS D AND E1 ARE DETERMINED AT DATUM H.
5. PIN ONE INDICATOR MUST BE LOCATED IN THE INDICATED ZONE.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.25	0.38	0.50
c	0.10	0.18	0.26
D	2.90	3.00	3.10
E	2.50	2.75	3.00
E1	1.30	1.50	1.70
e	0.85	0.95	1.05
L	0.20	0.40	0.60
L2	0.25 BSC		
M	0°	-	10°

#### STYLE 6:

1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR

### RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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